



Product Summary

- Low On-Resistance
- Excellent Gate Charge x $R_{DS(ON)}$ Product (FOM)
- Pb-Free Lead Plating
- RoHS and Halogen-Free Compliant
- 100% UIS Tested, 100% R_g Tested

	Value	Unit
	-100	V
	-2.0	V
	-30	A
	37	m
$R_{DS(ON)_{Typ}}$	50	m

D

G

o S

Ordering Information

Device	Package	# of Pins	Marking	M	M	o ²	M
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Drain-to-Source - e M 1

(1)	T_C 1 25°C	I_D	-30				A
	T_C 1 100°C		-19				

Avalanche Current⁽³⁾

-27

Avalanche Energy⁽³⁾

109

Power Dissipation⁽⁴⁾ T_C 1 25°C

96

T_C 1 100°C

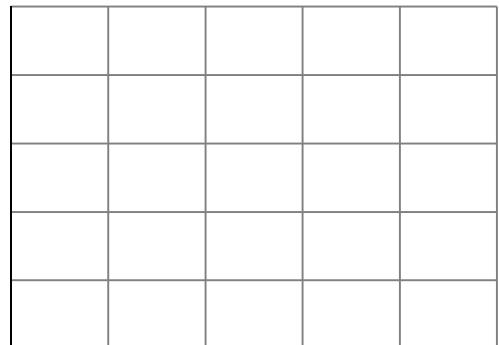
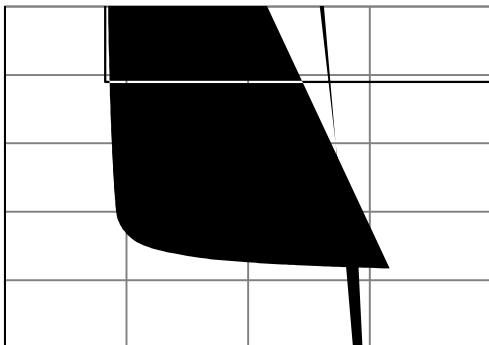
P_D

38

W

Junction & Storage Temperature Range

-55 to 150



Electrical Characteristics (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = -250\text{ A}, V_{GS} = 0\text{ V}$	-100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -80\text{ V}, V_{GS} = 0\text{ V}$ $T_J = 55^\circ\text{C}$			-1.0 -5.0	A
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ A}$	-1.0	-2.0	-3.0	V
Static Drain-Source ON-Resistance	$R_{DS(ON)}$	$V_{GS} = -10\text{ V}, I_D = -15\text{ A}$		37	50	m
		$V_{GS} = -4.5\text{ V}, I_D = -10\text{ A}$		50	66	m
Forward Transconductance	g_{FS}	$V_{DS} = -5\text{ V}, I_D = -15\text{ A}$		30		S
Diode Forward Voltage	V_{SD}	$I_S = -1\text{ A}, V_{GS} = 0\text{ V}$		-0.7	-1.0	V
Diode Continuous Current	I_S	$T_C = 25^\circ\text{C}$			-96	A

DYNAMIC PARAMETERS ⁽⁵⁾

Input Capacitance	C_{iss}			1412		pF
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}, V_{DS} = -50\text{ V}, f = 1\text{ MHz}$		222		pF
Reverse Transfer Capacitance	C_{rss}			2.6		pF
Gate Resistance	R_g	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ V}, f = 1\text{ MHz}$		10.2		

SWITCHING PARAMETERS ⁽⁵⁾

Total Gate Charge (@ $V_{GS} = -10\text{ V}$)	Q_g			20		nC
Total Gate Charge (@ $V_{GS} = -6.0\text{ V}$)	Q_g	$V_{GS} = 0\text{ to } -10\text{ V}$		12.6		nC
Gate Source Charge	Q_{gs}	$V_{DS} = -50\text{ V}, I_D = -15\text{ A}$		6.4		nC
Gate Drain Charge	Q_{gd}			3.3		nC
Turn-On DelayTime	$t_{D(on)}$			10.7		ns
Turn-On Rise Time	t_r	$V_{GS} = -10\text{ V}, V_{DS} = -50\text{ V}$		56		ns
Turn-Off DelayTime	$t_{D(off)}$	$R_L = 3.3\ \Omega, R_{GEN} = 6\ \Omega$		45		ns
Turn-Off Fall Time	t_f			81		ns
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -15\text{ A}, di_F/dt = -100\text{ A/s}$		51		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = -15\text{ A}, di_F/dt = -100\text{ A/s}$		130		nC

Thermal Performance

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	47	56	$^\circ\text{C/W}$

Typical Electrical & Thermal Characteristics

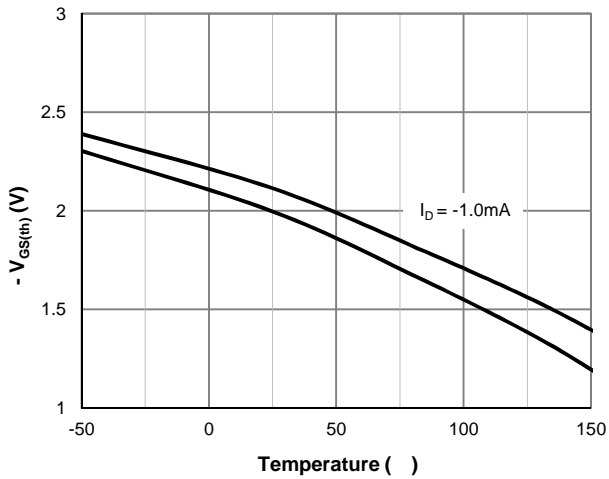
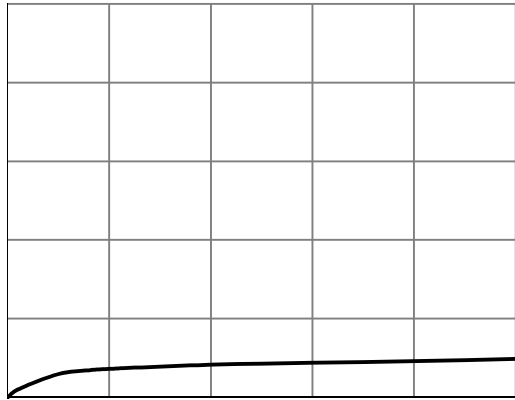


Figure 5: $V_{GS(th)}$ vs. Junction Temperature



TO-252-3L Package Information

